



规格书

SPECIFICATION

CUSTOMER NAME	客户名称:	
CUSTOMER NO.	客户编号:	
SERIES	系 列:	遥控信号接收模块
MODEL NO.	型 号:	XB-IRM选择指南-V1.8
DRAWING NO.	图 形 号:	

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

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APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署 STAMP盖章 DATE日期	

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研发部 戴海明 2022. 06. 08	品质部 黄自清 2022. 06. 08	工程部 庞军 2022. 06. 08	总经办 吴量 2022. 06. 08

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Quality core! Afterburner for Made in China!



东莞市溪榜电子有限公司

DONG GUAN XI BANG ELECTRONICS CO., LTD

IRM selection guide

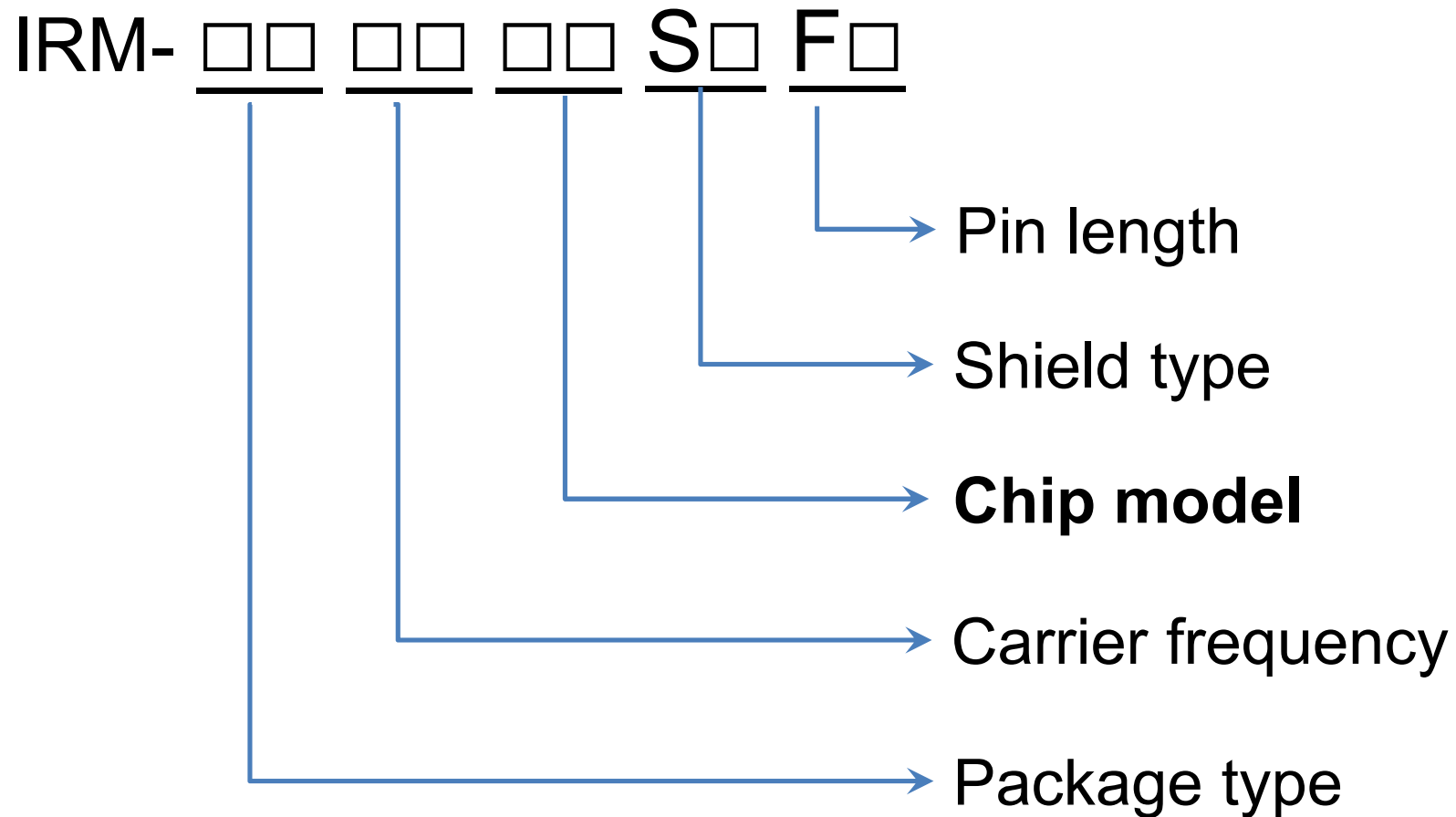
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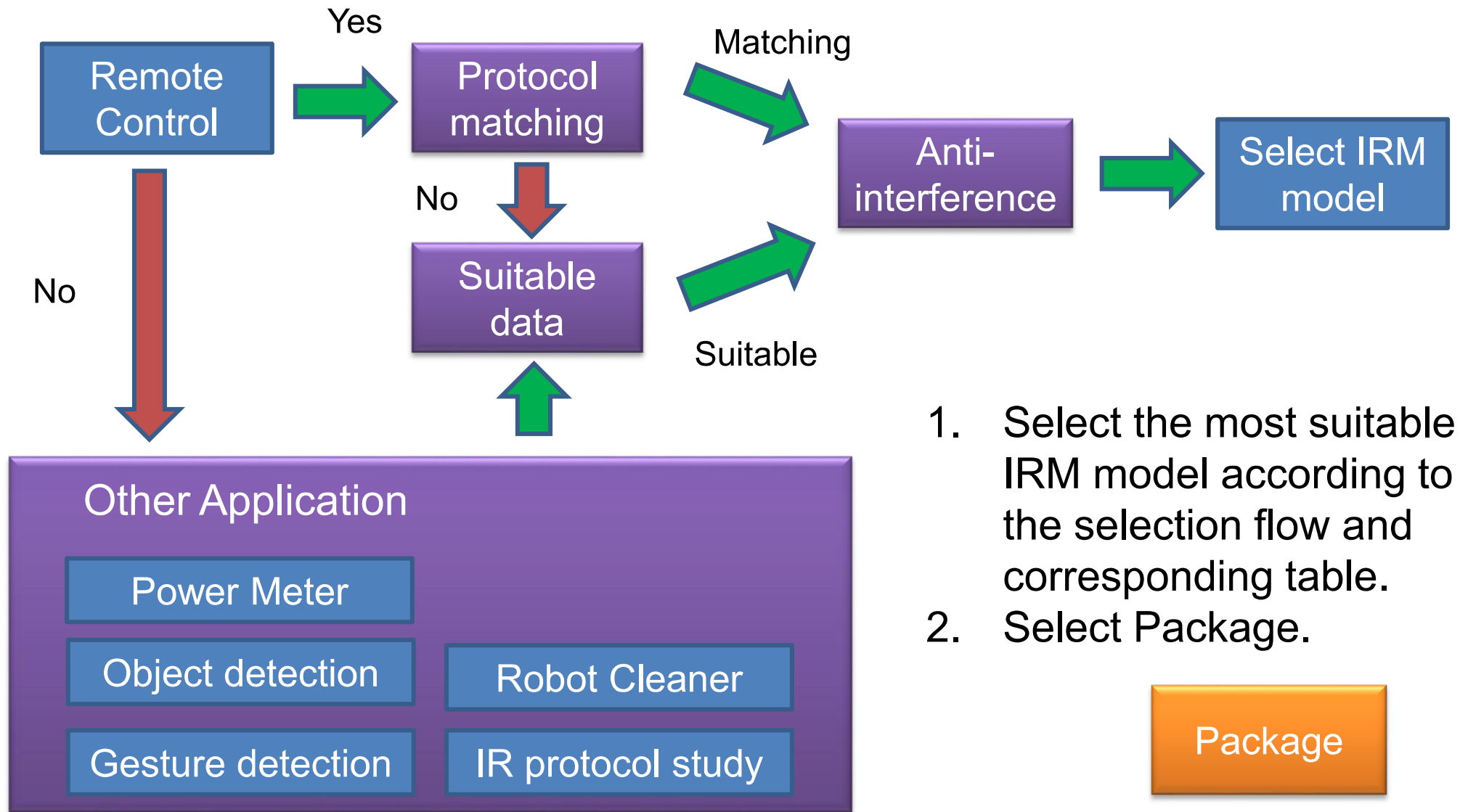
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XB-IRM Naming Rule



XB-Chip Model Selection Flow



XB-Protocol matching (1/3)

Protocol \ chip model	J	J2	J7	J8	J9
NEC	O	O	O	O	O
Toshiba	O	O	O	O	O
RCA	X	X	O	X	X
RC5 / RC6	O	O	O	O	O
Sony 12 Bit	O	O	O	O	X
Sony 15/20 Bit	X	O	O	X	X
Sharp	O	O	O	O	X
RCMM ¹⁾	X	X	X	X	X
XMPX1 ¹⁾	X	X	X	X	X
RECS-80	X	O	X	X	X
Xiaomi (Mi)	X	X	O	X	X
Continuous Data (Condition)	X	X	O >0.8 x actual_Burst	X	X

O...suitable, X...not recommended

1) Due to tight decoding margin, issues might occur under short or far distance

XB-Protocol matching (2/3)

Protocol \ chip model	J10	J11	J12	J13	J14	JF
NEC	O	O	O	O	O	O
Toshiba	O	O	O	O	O	O
RCA	O	O	O	O	O	O
RC5 / RC6	O	O	O	O	O	O
Sony 12 Bit	O	X	O	X	X	O
Sony 15/20 Bit	O	X	O	X	X	O
Sharp	O	O	X	O	O	O
RCMM ¹⁾	X	X	X	X	O	X
XMPX1 ¹⁾	X	X	X	X	O	O
RECS-80	X	O	X	X	O	X
Xiaomi (Mi)	O	X	O	X	O	O
Continuous Data (Condition)	O >0.8 x actual_Burst	O Burst ≤ 700us	O >0.5 x actual_Burst	O Burst ≤ 700us	O Burst ≤ 700us	O Unlimited

O...suitable, X...not recommended

1) Due to tight decoding margin, issues might occur under short or far distance

XB-Protocol matching (3/3)

Protocol \ chip model	J15	J16	T	M	M2	M3	M6
NEC	O	O	O	O	O	O	O
Toshiba	O	O	O	O	O	O	O
RCA	X	O	X	O	X	X	O
RC5 / RC6	O	O	O	O	O	O	O
Sony 12 Bit	O	O	O	O	O	O	O
Sony 15/20 Bit	X	O	X	X	O	X	O
Sharp	O	O	O	X	X	O	O
RCMM ¹⁾	X	X	X	X	X	X	X
XMPX1 ¹⁾	X	X	X	X	X	X	X
RECS-80	X	X	X	O	X	X	O
Xiaomi (Mi)	X	O	X	X	O	X	O
Continuous Data (Condition)	X	O >0.8 x actual_Burst	X	O Burst ≤ 500us	O Burst ≤ 1.2ms	X	X

O...suitable, X...not recommended

1) Due to tight decoding margin, issues might occur under short or far distance

XB-Suitable data (1/2)

	J	J2	J7	J8	J9
Min. burst time (us)	300	150	300	250	300
Min. gap time (us)	350	275	350	300	350
Min. pause time (ms)	25	9	1 ($>0.8 \times$ actual_Burst)	25	40

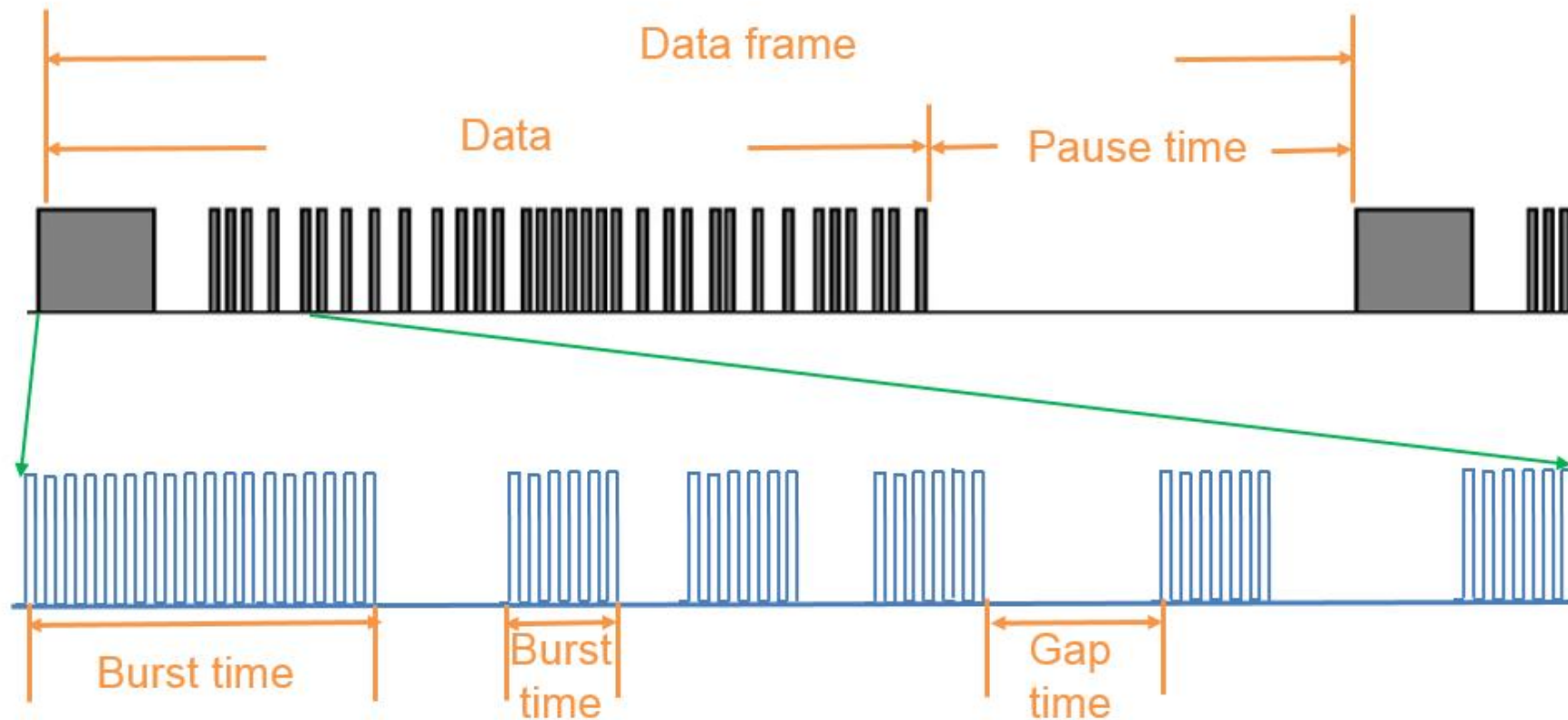
	J10	J11	J12	J13	JF
Min. burst time (us)	350	150	350	300	200
Min. gap time (us)	400	300	400	350	300
Min. pause time (ms)	1 ($>0.8 \times$ actual_Burst)	>0.3 (Burst $\leq$ 700us)	>0.83 ($>0.5 \times$ actual_Burst)	>0.35 (Burst $\leq$ 700us)	0

XB-Suitable data (2/2)

	J14	J15	J16
Min. burst time (us)	150	300	300
Min. gap time (us)	275	350	350
Min. pause time (ms)	>0.275 (Burst $\leq$ 700us)	25	(>0.8 x actual_Burst)

	T	M	M2	M3	M6
Min. burst time (us)	265	160	265	210	160
Min. gap time (us)	370	265	370	320	265
Min. pause time (ms)	22	1 (Burst $\leq$ 500us)	1 (Burst $\leq$ 1.2ms)	22	30 (Burst $\leq$ 1.2ms)

XB-Noun definition



For detailed instructions, please refer to the IRM application Note.

XB-Anti-interference(1/2)

interference	J	J2	J7	J8	J9
Incandescent	-	-	++	-	+
Fluorescent	+	+	+	+	+
Wifi	++	-	++	++	++
VCC Ripple	++	++	++	++	++

interference	J10	J11	J12	J13	JF
Incandescent	++	+	+	+	-
Fluorescent	+	+	++	++	+
Wifi	++	-	++	++	++
VCC Ripple	-	+	++	+	-

++ : Best suppression, + : suppression in most case , - : possibility of noise pulses

XB-Anti-interference(2/2)

interference	J14	J15	J16
Incandescent	+	+	+
Fluorescent	+	++	++
Wifi	++	++	++
VCC Ripple	++	++	++

interference	T	M	M2	M3	M6
Incandescent	+	-	+	-	++
Fluorescent	+	+	+	++	-
Wifi	+	+	++	+	-
VCC Ripple	++	-	-	+	-

++ : Best suppression, + : suppression in most case , - : possibility of noise pulses

XB Other Application

Application	Chip model	Note
Power Meter (Continuous transmission)	J12, JF	JF: needn't Pause time J12 : High sensitivity
Object/Gesture detection	J, JF	JF: Better consistency and needn't Pause time.
Robot Cleaner	J10, JF	JF: Better consistency.
IR protocol study	JW, JF	JW : Carrier wave output(without Demodulator) JF : With Demodulator

Dip



8.25 x 6.00 x 5.60

XB-IRM-36xx / 35xx series

- XB-IRM-36xx (Vout-GND-Vcc)
- XB-IRM-35xx (Vout-Vcc-GND)



6.27x4.36x3.10

XB-IRM-66xx series

- XB-IRM-66xx (Vout-GND-Vcc)



7.76x6.80x5.60(橢圓Lens)

XB-IRM-86xx series

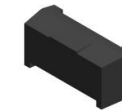
- XB-IRM-86xx (Vout-GND-Vcc)



SMD

XB-IRM-V Series : side view

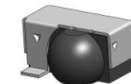
- XB-IRM-V3xx



6.60 x 3.00 x 2.50

- XB-IRM-V5xx

5.30x3.80x2.65



- XB-IRM-V8xx

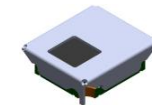


6.60x3.00x3.20

XB-IRM-H Series : top view

- XB-IRM-H2xx

5.10x4.60x1.45



- XB-IRM-H3xx



6.60x3.00x2.50

- XB-IRM-H5xx

5.30x2.90x3.65



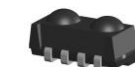
- XB-IRM-H6xx



5.00x4.00x4.00

- XB-IRM-H8xx

6.60x3.00x3.20



- XB-IRM-H9xx



5.00x4.00x2.00